IN THE CLAIMS

Please amend the claims as follows:

1-21. (Canceled)

22. (Currently Amended) A fluid ejection device comprising:

a heating element on a substrate surface; and

a cover layer on the substrate surface, the cover layer defining a firing chamber formed about the heating element and defining a nozzle over the firing chamber, wherein the cover layer includes a primer layer, a chamber layer, a nozzle layer, and a top coat layer, ~~first layer and a second layer,~~ wherein at least one of the ~~first and second~~ layers includes a dry film.

23. (Currently Amended) The fluid ejection device of claim 22 wherein the primer layer and the chamber layer ~~first layer~~ at least partially define ~~defines~~ the firing chamber.

24. (Currently Amended) The fluid ejection device of claim 22 wherein the nozzle ~~second~~ layer at least partially defines the nozzle.

25. (Currently Amended) The fluid ejection device of claim 22 further comprising a third layer between the nozzle layer and the chamber layer ~~first and second layers~~, wherein the third layer comprises a photon barrier layer and at least partially defines the nozzle ~~firing chamber~~.

26. (Currently Amended) The fluid ejection device of claim 22 [[25]] wherein the primer layer, the chamber layer, and the nozzle layer ~~first, second and third layers~~ include dry film.

27. (Previously Presented) The fluid ejection device of claim 22 wherein the cover layer includes at least two SU8 layers.

28. (Currently Amended) A fluid ejection device comprising:

a resistor on a substrate surface;

a first polymer [[SU8]] layer formed over the substrate surface and surrounding ~~that surrounds~~ the resistor; [[and]]

a second polymer [[SU8]] layer formed over [[on]] the first polymer [[SU8]] layer and defining a nozzle; and

a top coat layer defining a countersunk bore corresponding to the nozzle.

29. (Currently Amended) The fluid ejection device of claim 28 wherein at least one of the first and second polymer layers comprises ~~the second~~ SU8 ~~layer includes a nozzle corresponding to the resistor~~.

30. (Currently Amended) The fluid ejection device of claim 28 wherein one of the first and second polymer layers [[layer]] includes a dry film.

31. (Currently Amended) A method comprising:

forming a heating element on a substrate surface of a substrate with a fluid slot;

defining a firing chamber formed about the heating element with a first layer on the substrate surface;

defining a nozzle over the firing chamber in a second layer; and

exposing the substrate surface by offsetting at least one outer edge of the first layer from a respective outer edge of the substrate, wherein fluid flows through the fluid slot in the substrate to the firing chamber to eject from the nozzle.

32. (Currently Amended) The method of claim 31 wherein the first layer and the second layer comprise [[are]] SU8 ~~layers~~.

33. (Currently Amended) The method of claim 31 further comprising forming at least one of the first or second layers [[layer]] using a lost wax method.

34. (Currently Amended) A fluid ejection device comprising:

a resistor on a substrate surface; and

a first polymer layer defining a firing chamber formed over the resistor; [[and]]

a second polymer layer defining a nozzle over the firing chamber; and

a top coat layer defining a countersunk bore associated with the nozzle,

wherein at least one of the first and second layers includes a dry film.

35. (Previously Presented) The fluid ejection device of claim 34 further comprising a third layer between the first and second layers, wherein the third layer at least partially defines the firing chamber.

36. (Previously Presented) The fluid ejection device of claim 35 wherein the first, second and third layers include dry film.

37. (Previously Presented) The fluid ejection device of claim 35 wherein the first and second layers are SU8 layers.

38. (Currently Amended) A fluid ejection device comprising:

a heating element supported by a substrate surface; and

a cover layer supported by the substrate surface, the cover layer defining a firing chamber formed about the heating element and defining a nozzle over the firing chamber,

wherein the cover layer includes a plurality of layers including a primer layer supported by the substrate surface, wherein at least one outer edge of at least one other of the cover layers is ~~the cover layer~~ is offset from a respective outer edge of the primer layer ~~substrate~~ to expose a ~~the substrate~~ surface of the primer layer.

39. (Previously Presented) The fluid ejection device of claim 38 wherein the cover layer includes at least two SU8 layers.

40. (Previously Presented) The fluid ejection device of claim 38 wherein the cover layer includes a countersunk bore about the nozzle.

41. (Previously Presented) The fluid ejection device of claim 38 wherein the cover layer includes a top coat substantially smoothing an upper surface of the cover layer.

42. (Previously Presented) The fluid ejection device of claim 41 wherein the top coat includes a non-wetting surface.

43. (New) The fluid ejection device of claim 22 wherein at least one outer edge of the chamber layer is offset from a respective outer edge of the primer layer to expose a surface of the primer layer.

44. (New) The fluid ejection device of claim 28 further comprising a primer layer formed between the substrate surface and the first polymer layer.

45. (New) The fluid ejection device of claim 44 wherein at least one outer edge of the first polymer layer is offset from a respective outer edge of the primer layer to expose a surface of the primer layer.

46. (New) The method of claim 31 wherein the substrate surface includes a primer layer, wherein the primer layer has a surface that is exposed from the offset outer edge of the first layer.